

VinMin = 6.0V VinMax = 18.0V Vout = 5.0V Iout = 2.0A

Device = TPS54232DR Topology = Buck Created = 2017-12-30 03:12:45.359 BOM Cost = \$2.11 Total Pd = 1.73W Footprint = 188.0 mm<sup>2</sup>

BOM Count = 15 tSim Id = 2

# **WEBENCH** <sup>®</sup> Thermal Simulation Report

Design: 4530725/56 TPS54232DR Leawood R2 TPS54232DR 6.0V-18.0V to 5.00V @ 2.0A

## **Operating Condition**

Name	Value		
VIN_OP	18.0V		
IOUT OP	2.0A		

### **Ambient Temperature**

Name	Temperature				
Ambient_plus_Z	30.0				
Ambient_minus_Z	30.0				

#### Air Flow

Name	Direction			
Flow_Type	Convection			
Flow_Rate	0.0LFM			
Flow Direction	Top to Bottom			

### **Edge Temperature**

Name	Temperature	Thermal Type				
Edge_plus_X (Right)		Insulated				
Edge_minus_X (Left)		Insulated				
Edge_plus_Y (Top)		Insulated				
Edge_minus_Y (Bottom)		Insulated				

#### **My Comments**

No comments

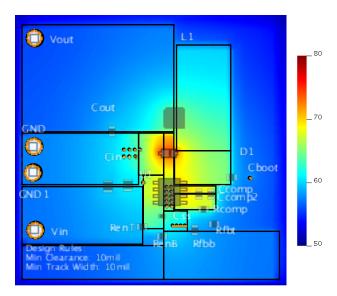
#### **BOM**

Component Name(s)	Part Number	Max Temp	Power Dissipation	Manufacture	Properties	Qty	Price	Footprint
pcb_bottom		65°C						
L1	XAL4030-682MEB	66°C	0.297W	Coilcraft	L=6.8E-6H DCR=0.0674Ohm	1	\$0.72	XAL4030 25.0 mm <sup>2</sup>
Cin	GRM32ER61E226KE15L	61°C	0.00W	MuRata	VDC=25.0V ESR=0.002Ohm IRMS=3.67A Cap=2.2E-5F	2	\$0.18	1210 14.7 mm <sup>2</sup>
Cout	C2012X5R1A476M125AC	60°C	0.00W	TDK	Cap=4.7E-5F ESR=0.00294Ohm IRMS=3.80451A VDC=10.0V	1	\$0.29	0805 6.75 mm <sup>2</sup>

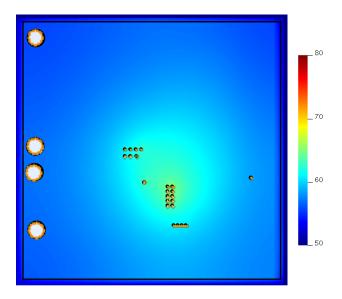
# WEBENCH® Design

Component Name(s)	Part Number	Max Temp	Power Dissipation	Manufacture	Properties	Qty	Price	Footprint
U1	TPS54232DR	109°C	0.662W	Texas Instruments		1	\$0.55	
								D0008A 56.58 mm <sup>2</sup>
D1	SS24FL	0°C	0.768W	Fairchild Semiconductor	VRRM=40.0V VFatIo=0.55V	1	\$0.07	SOD-123F 11.7 mm <sup>2</sup>
pcb_top		74°C						

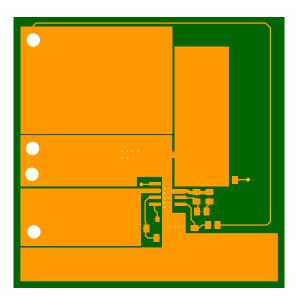
# Thermal Images



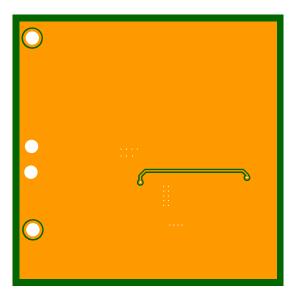
Thermal Top Image



Thermal Bottom Image

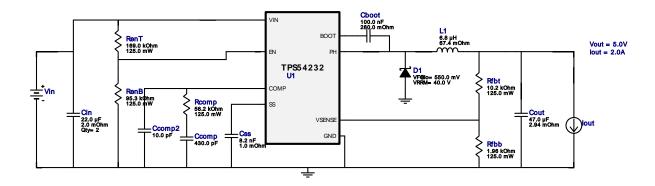


PCB Top Image



PCB Bottom Image

#### Schematic



#### Design Assistance

1. TPS54232 Product Folder: http://www.ti.com/product/TPS54232: contains the data sheet and other resources.

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